/ Descriptions

BRCO7350UMC CMOS

200mA 55V

BRCO7350UMC CMOS

/ Features

55V
200mA
800mV@Iout=100mA
2.5μA
±50ppm/
±2
PSRR 70dB@1kHz
SOT23-3

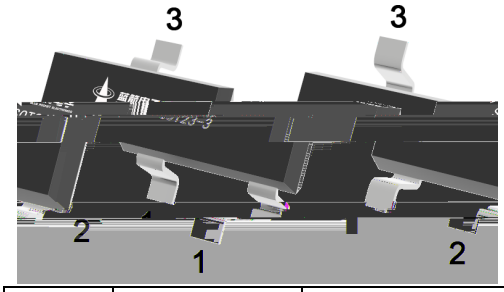
/ Applications

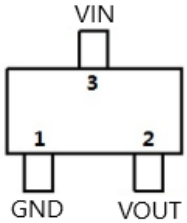
/

/ Equivalent Circuit



/ Pinning



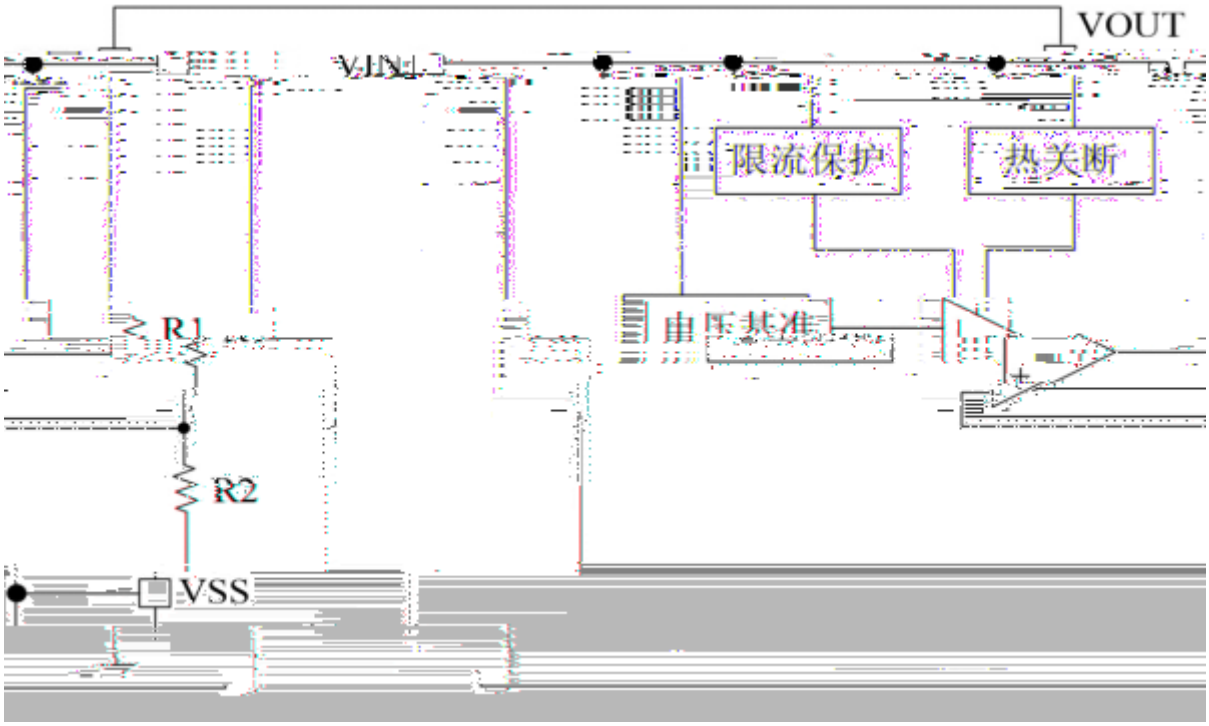


1	GND		3	VIN	
2	VOUT				

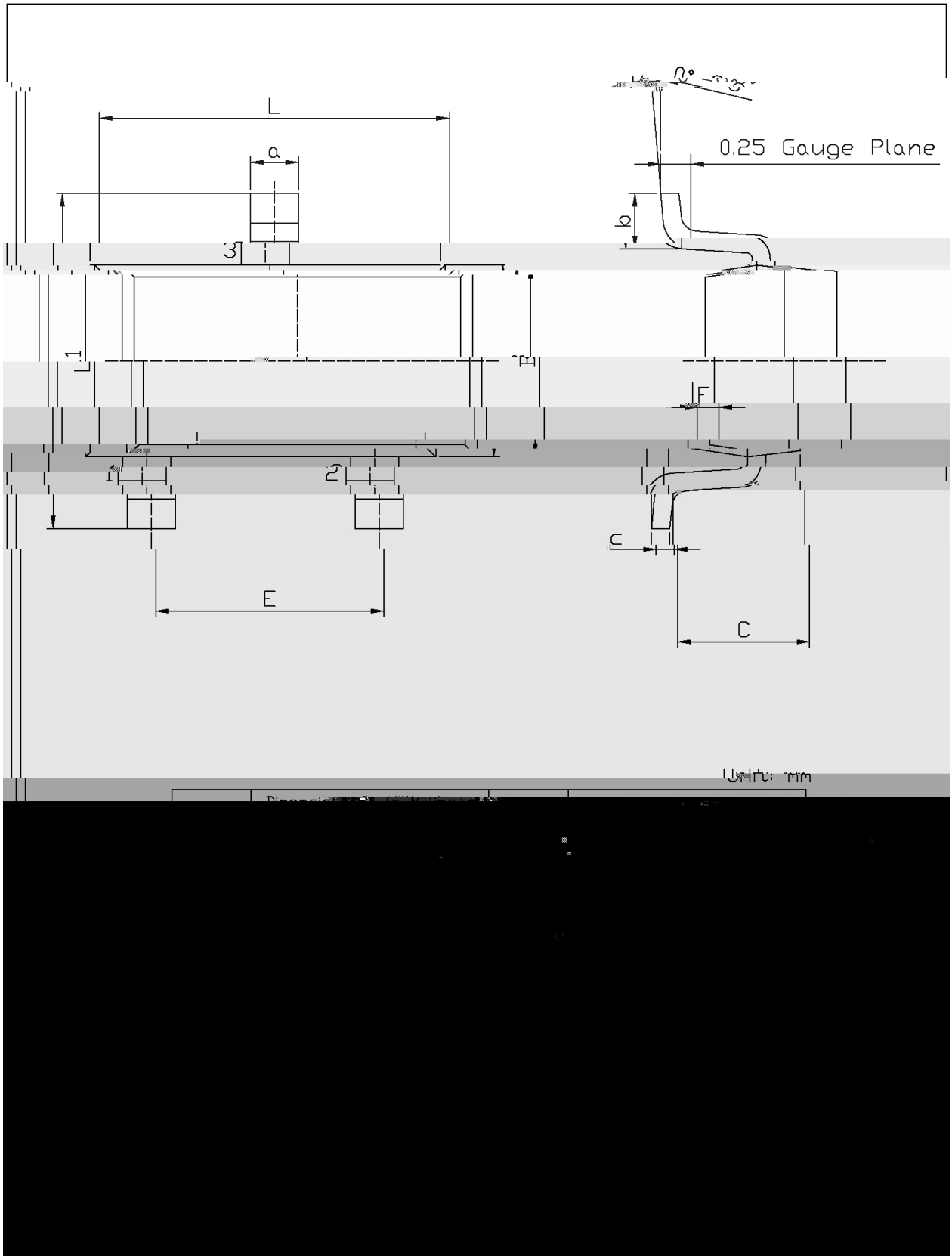
	V_{IN_MAX}	55	V
	V_{IN}	45	V
	I_{OUT}	250	mA
	P_D	0.3	W
	T_{stg}	-40 to +125	°C
	T_{OP}	-10 to +85	

	V_{IN}				45	V
	V_{OUT}		V_{OUT} *0.98		V_{OUT} *1.02	V
	I_{SS}	I_{OUT}=0mA		2.5	6	uA
	I_{OUT}			200		mA
	L_{LIM}			350		mA
	V_{DROP}	I_{OUT}=100mA		800		mV
	V_{LOAD}	1mA ≤ I_{OUT} ≤ 100mA	-50	10	50	mV
	V_{LINE}	V_{OUT}+2V ≤ V_{IN} ≤ 45V I_{OUT}=10mA		0.01	0.2	%/V
	V_{OUT}/ (T_A*V_{OUT})	I_{OUT}=1mA -40 ≤ T_A ≤ 85		± 50		ppm/
	PSRR	f=100Hz		80		dB
		f=1kHz		70		
		f=10kHz		50		
	T_{SD}			160		
	T_{SD}			25		

/ Functionl Block Diagram



/ Package Dimensions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

1 150 180 60 90sec;

2 245±5 5±0.5sec;

3 2 10 /sec.

1.Preheating:150~180 , Time:60~90sec.

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL